

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ097N10NS5	**Issued**	08. February 2022
MA#	MA002669412		
Package	PG-TSDSON-8-26	**Weight***	36.82 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.734	1.99	1.99	19936	19936
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		67	
	non noble metal	zinc	7440-66-6	0.010	0.03		267	
	non noble metal	iron	7439-89-6	0.197	0.53		5344	
	non noble metal	copper	7440-50-8	7.988	21.70	22.27	216981	222659
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	760	760
encapsulation	organic material	carbon black	1333-86-4	0.037	0.10		995	
	plastics	epoxy resin	-	1.887	5.13		51256	
	inorganic material	silicondioxide	60676-86-0	16.397	44.54	49.77	445384	497635
leadfinish	non noble metal	tin	7440-31-5	0.395	1.07	1.07	10736	10736
plating	noble metal	silver	7440-22-4	0.020	0.06	0.06	552	552
solder	non noble metal	tin	7440-31-5	0.020	0.05		535	
	noble metal	silver	7440-22-4	0.025	0.07		668	
	non noble metal	lead	7439-92-1	0.940	2.55	2.67	25533	26736
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			34	
	non noble metal	zinc	7440-66-6	0.005	0.01		138	
	non noble metal	iron	7439-89-6	0.101	0.28		2751	
	non noble metal	copper	7440-50-8	4.112	11.17	11.46	111702	114625
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			32	
	non noble metal	zinc	7440-66-6	0.005	0.01		128	
	non noble metal	iron	7439-89-6	0.094	0.26		2553	
	non noble metal	copper	7440-50-8	3.816	10.36	10.63	103648	106361
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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